

What is claimed is:

1. A method of forming a layered polishing pad comprising:
 - a) forming a first double-sided adhesive layer on a bottom surface of a subpad;
 - b) forming a second double-sided adhesive layer on a top surface of the subpad;
 - c) providing a polishing pad layer having a lower surface; and
 - d) adhering the polishing pad layer to the subpad by pressing the polishing pad layer lower surface against the second adhesive layer.
2. The method of claim 1, further including after act b) therein:
 - a) forming an opening that extends through the first adhesive layer, the subpad and the second adhesive layer;
 - b) providing the polishing pad layer with a window; and
 - c) in said adhering, aligning the window to the opening.
3. The method of claim 1, wherein forming the first and second double-sided adhesive layers includes laminating the first and second double-sided adhesive layers as pressure-sensitive adhesive (PSA) layers to the bottom and top surfaces of the subpad, respectively.
4. The method of claim 1, including respectively providing material for the subpad and the first and second double-sided adhesive layers in roll-good form.
5. The method of claim 1, wherein the acts therein are carried out in the order presented.
6. A method of forming a layered polishing pad, comprising:
 - a) laminating a first double-sided adhesive layer onto a bottom surface of a subpad;
 - b) laminating a second double-sided adhesive layer on a top surface of the subpad;
 - c) forming an opening through the first adhesive layer, the subpad and the second adhesive layer; and
 - d) securing a polishing pad having a window formed therein, to the subpad with the second adhesive layer, such that the window is aligned to the opening.

7. The method of claim 6, including providing respective materials for the subpad, the first double-sided adhesive layer and the second double-sided adhesive layer in roll-good form.
8. The method of claim 6, wherein act b) is performed before act c) and wherein laminating the second double sided adhesive layer to the subpad includes:
- a) feeding the subpad material and the first double-sided adhesive layer material through nip-rollers to form a laminated structure; and
 - b) maintaining the laminated structure exiting the nip rollers substantially horizontally for a travel length sufficient for the laminated structure to cure.
9. A method of forming a layered polishing pad comprising:
- a) sequentially forming respective adhesive layers on opposing surfaces of a subpad to form a double-laminated subpad;
 - b) forming an opening through the double-laminated subpad; and
 - c) securing a polishing pad having a window, to the double-laminated subpad by pressing a polishing pad lower surface against one of the adhesive layers such that the window and opening form a through optical path that includes no adhesive layer.
10. A method of forming a layered polishing pad comprising:
- a) sequentially forming respective adhesive layers on opposing surfaces of a subpad to form a double-laminated subpad; and
 - b) securing a polishing pad to the double-laminated subpad by pressing a polishing pad lower surface against one of the adhesive layers.